Product Change Notification: DSNO-05ITIC954

Date:

08-Oct-2026

Product Category:

Ethernet Phys, Ethernet Switches

Notification Subject:

CCB 8538 Final Notice: Qualification of new lead frame with 160x160 mils lead frame paddle size for KSZ8041MLL, KSZ8863FLL, SPNY801088-TR, KSZ8863FLL-TR, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8863MLL and KSZ8863RLL catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Affected CPNs:

DSNO-05ITIC954_Affected_CPN_10082026.pdf
DSNO-05ITIC954_Affected_CPN_10082026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of new lead frame with 160x160 mils lead frame paddle size for KSZ8041MLL, KSZ8863FLL, SPNY801088-TR, KSZ8863FLL-TR, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8863MLL and KSZ8863RLL catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Orient Semiconductor Electronics, Ltd (OSE)	Orient Semiconductor Electronics,	No

			Ltd (OSE)	
Wire Material	Au		Au	No
Die Attach Material	EN4900G		EN4900G	No
Molding Compound Material	CEL-9200HF		CEL-9200HF	No
Lead-Frame Material	C7025		C7025	No
Lead-Frame Paddle Size	120x120 mils	205x205 mils	160x160 mils	Yes
Lead-Frame Design	See Pre and Post Change Summary Attachment for Comparison.			Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying a new lead frame with 160x160 mils lead frame paddle size.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 December 2026 (date code: 2652)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2026					**>**	**December 2026**			
Work Week	40	41	42	43	44		49	50	51	52
Qual Report Availability		**x**								
Final PCN Issue Date		**x**								
Estimated Implementation Date										**x**

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Note: This is a qualification by similarity (QBS) to CCB# 6059.

Revision History: October 08, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-05ITIC954_Pre and_Post Change Summary.pdf
PCN_DSNO-05ITIC954_Qualification Report_CCB.6059.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

DSNO-05ITIC954 - CCB 8538 Final Notice: Qualification of new lead frame with 160x160 mils lead frame paddle size for KSZ8041MLL, KSZ8863FLL, SPNY801088-TR, KSZ8863FLL-TR, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8863MLL and KSZ8863RLL catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Affected Catalog Part Numbers (CPN):

KSZ8041MLL

KSZ8863FLL

SPNY801088-TR

KSZ8863FLL-TR

KSZ8041MLLI

KSZ8041MLL-TR

KSZ8041MLLI-TR

KSZ8863MLL

KSZ8863RLL

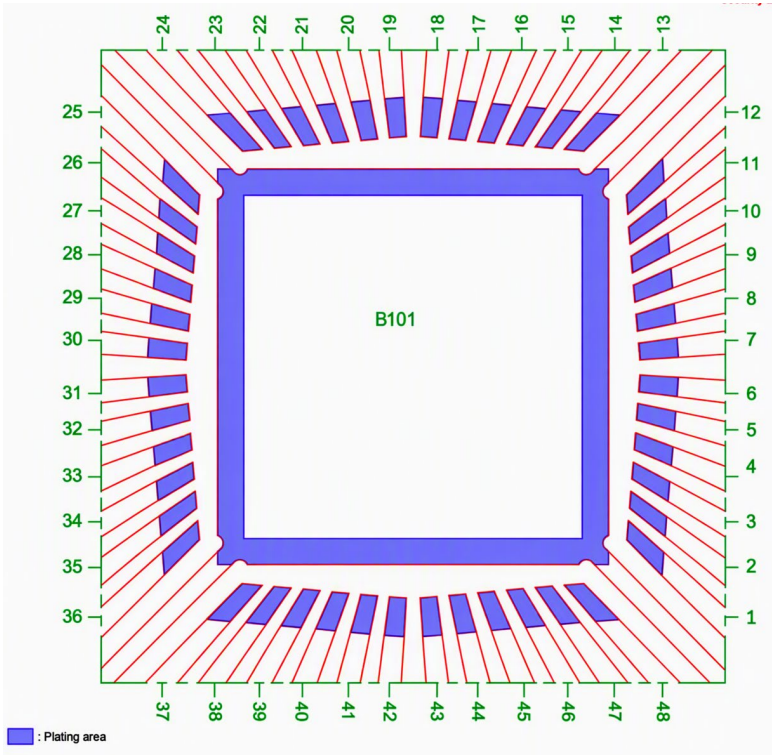
CCB 8538
Pre and Post Change Summary
PCN #: DSNO-05ITIC954



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Lead Frame Comparison

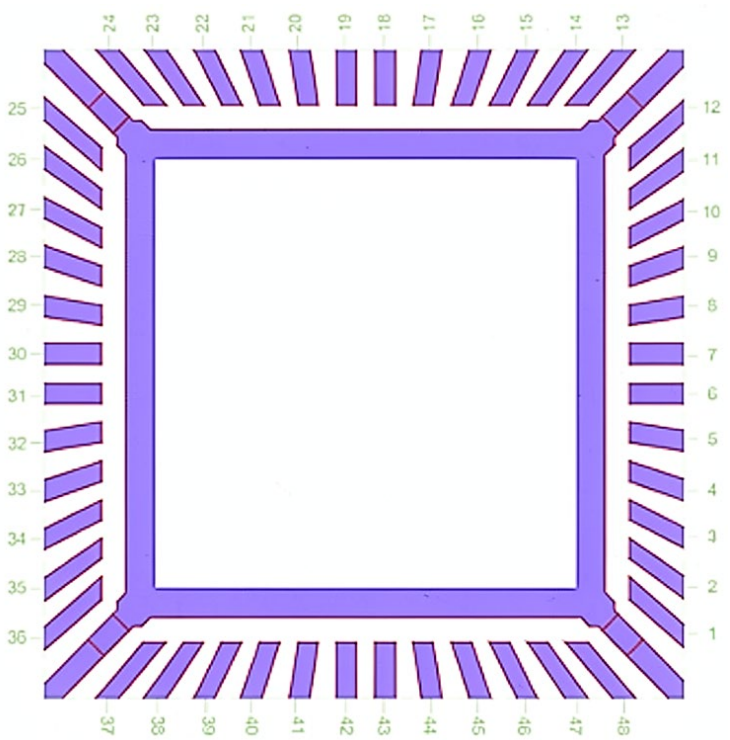
Pre Change



Note: Not to scale

Lead-Frame Paddle Size	120 x 120 mils

Post Change



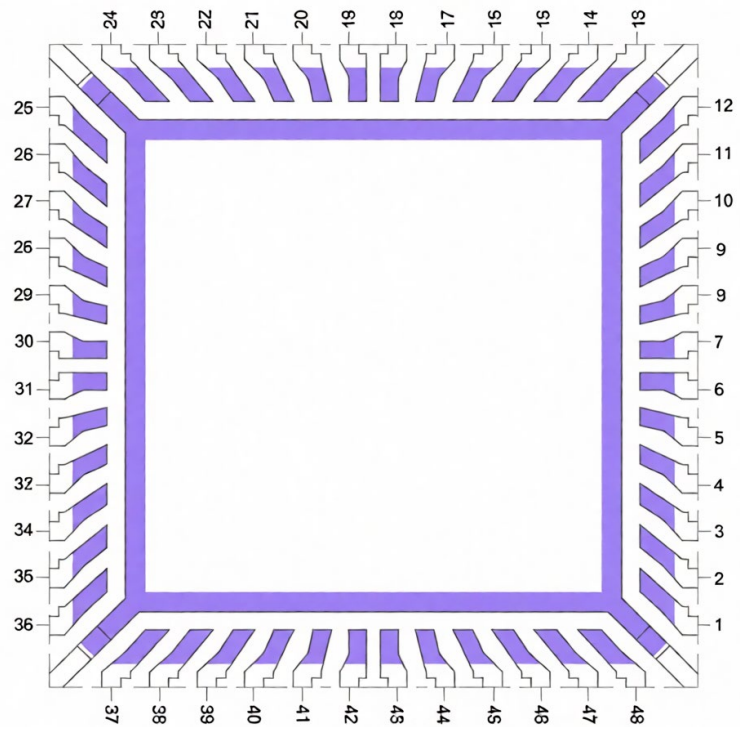
Note: Not to scale

Lead-Frame Paddle Size	160 x 160 mils

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Lead Frame Comparison

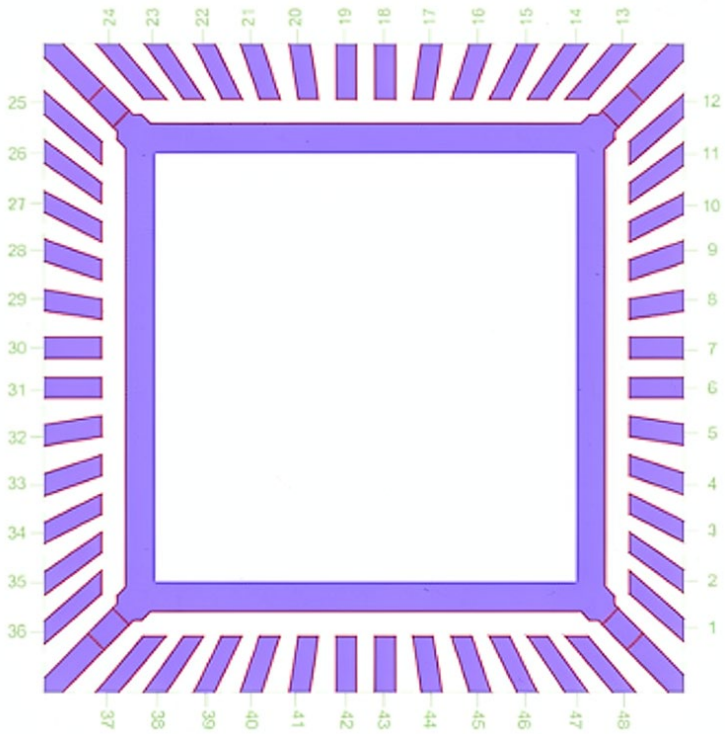
Pre Change



Note: Not to scale

Lead-Frame Paddle Size	205 x 205 mils

Post Change



Note: Not to scale

Lead-Frame Paddle Size	160 x 160 mils

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PACKAGE QUALIFICATION REPORT

PCN #: DSNO-05ITIC954

Date:
November 8, 2023

Qualification of new lead frame with 160x160 mils lead frame paddle size for KSZ8041MLL, KSZ8863FLL, SPNY801088-TR, KSZ8863FLL-TR, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8863MLL and KSZ8863RLL catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.

Purpose: **Qualification of new lead frame with 160x160 mils lead frame paddle size for KSZ8041MLL, KSZ8863FLL, SPNY801088-TR, KSZ8863FLL-TR, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8863MLL and KSZ8863RLL catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package at OSE assembly site.**

I. Summary:

The purpose of this report is to qualify EN4900G Die Attach Epoxy in 48L LQFP 7x7x1.4mm using 36063 mask at OSE per CCB# 6059 and following guidelines established in Microchip specification QCI-39000, “Worldwide Quality Conformance Requirements” .

II. Conclusion:

Based on the results, EN4900G Die Attach Epoxy in 48L LQFP 7x7x1.4mm at OSE complies with the reliability guidelines implemented in the qualification plan. Therefore, this package can be released to production as per guidelines established in Microchip specification QCI-39000, “Worldwide Quality Conformance Requirements.”

III. Device Description:

Device	KSZ8721BLI
Document Control Number	ML1120230024
Document Revision	A
CCB No.	6059

IV. Qualification Material:

Test Lot	Lot 1	Lot 2	Lot 3
WAFER LOT	TSMC: TC03924020698.200 Tempe: TMPE223434178.100	TSMC: TC03924020698.200 Tempe: A100	TSMC: TC03924020698.200 Tempe: TMPE223434178.100
ASSEMBLY LOT	OSE-240800020.000	OSE-240800021.000	OSE-240800022.000
PACKAGE	48L LQFP 7x7x1.4mm	48L LQFP 7x7x1.4mm	48L LQFP 7x7x1.4mm
QUAL TESTS	PRECOND, HTSL, HAST, UHAST, TC	PRECOND, HAST, UHAST, TC	PRECOND, HAST, UHAST, TC

V. Bill of Materials:

Misc.	**Assembly site**	OSE, Taiwan
	MP Code (MPC)	36063TCAAA01
	Part Number (CPN)	KSZ8721BLI
Lead-Frame	**Paddle size**	160x160 mil
	Material	C7025
	Treatment	Non- Rough
	Process	Stamped
	Lead-lock	No
	Part Number	02-A164-300R
	Lead Plating	Matte Tin
Bond Wire	**Material**	Au
Bottom Die Attach	**Part Number**	EN4900G
	Conductive	Yes
Top Die Attach	**Part Number**	QMI-550
	Conductive	No
MC	**Part Number**	CEL-9200HF
PKG	**PKG Type**	LQFP
	MSL	3
	Pin/Ball Count	48L
	PKG width/size	7x7x1.4mm

VI. Qualification Data:

Package Preconditioning

Test Method/Condition	JEDEC J-STD-020D and JESD22-A113F, MSL Level 3 soak and 260°C peak Reflow Temperature
Lot #	Results (Fail/Pass)
Lot 1	0/264
Lot 2	0/264
Lot 3	0/264
Result	Pass

Post testing was conducted at +25◦C, +85◦C

HAST (Highly Accelerated Temperature and Humidity Stress Test)

Test Method/Condition	JESD22-A110, Vin = +3.3V, Ta = +130°C/85%RH, 96 HRS Min SS = 77 units
Lot #	Results (Fail/Pass)
Lot 1	0/82
Lot 2	0/82
Lot 3	0/82
Result	Pass

Pre and Post testing was conducted at +25◦C, +85◦C

UNBIASED HAST

Test Method/Condition	JESD22-A118, Ta = +130°C/85%RH, 96HRS Min SS = 77 units
Lot #	Results (Fail/Pass)
Lot 1	0/82
Lot 2	0/82
Lot 3	0/82
Result	Pass

Pre and Post testing was conducted at +25◦C

Temperature Cycling

Test Method/Condition	JESD22-A104, Ta = -65°C/+150 °C, 500 CYC Min SS = 77 units
Lot #	Results (Fail/Pass)
Lot 1	0/82, WPS after TCY: 0/5
Lot 2	0/82
Lot 3	0/82
Result	Pass

Pre and Post testing was conducted at +25◦C, +85◦C

High Temperature Storage Life

Test Method/Condition	JESD22-A103, Ta = +175 °C, 504HRS Min SS = 45 units
Lot #	Results (Fail/Pass)
Lot 1	0/50
Result	Pass

Pre and Post testing was conducted at +25◦C, +85◦C

VII. Wire Pull/Ball Shear/Wire Sweep/Physical Dimension

Lot #1:

Test Item	Sample Size/ Unit	Comment
Wire Pull	40 wires/5	Pass
Ball Shear	40 balls/5	Pass
Solderability	27	Pass
Physical Dimension	10	Pass

Lot #2

Test Item	Sample Size/ Unit	Comment
Wire Pull	40 wires/5	Pass
Ball Shear	40 balls/5	Pass
Solderability	27	Pass
Physical Dimension	10	Pass

Lot #3

Test Item	Sample Size/ Unit	Comment
Wire Pull	40 wires/5	Pass
Ball Shear	40 balls/5	Pass
Solderability	27	Pass
Physical Dimension	10	Pass